

Dual P-Channel Enhancement Mode Power MOSFET

Description

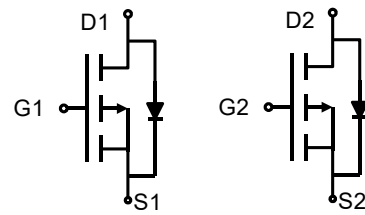
The G170P03S2 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.

General Features

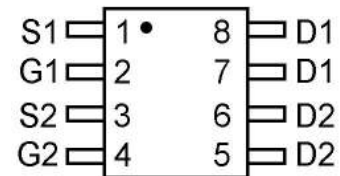
- V_{DS} -30V
- I_D (at $V_{GS} = -10V$) -9A
- $R_{DS(ON)}$ (at $V_{GS} = -10V$) < 18m Ω
- $R_{DS(ON)}$ (at $V_{GS} = -4.5V$) < 25m Ω
- 100% Avalanche Tested
- RoHS Compliant

Application

- Power switch
- DC/DC converters



Schematic diagram



pin assignment



SOP-8

Ordering Information

| Device | Package | Marking | Packaging |
|-----------|------------|---------|--------------|
| G170P03S2 | SOP-8 Dual | G170P03 | 4000pcs/Reel |

Absolute Maximum Ratings $T_C = 25^\circ C$, unless otherwise noted

| Parameter | Symbol | Value | Unit |
|--|----------------|------------|------------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Continuous Drain Current | I_D | -9 | A |
| Pulsed Drain Current (note1) | I_{DM} | -36 | A |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Power Dissipation | P_D | 1.4 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 To 150 | $^\circ C$ |

Thermal Resistance

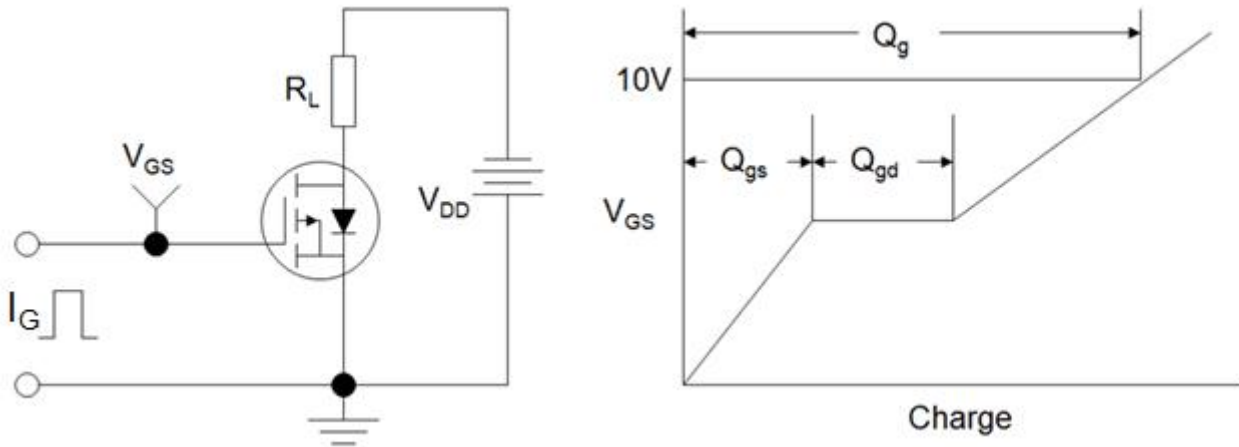
| Parameter | Symbol | Value | Unit |
|---|------------|-------|--------------|
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 90 | $^\circ C/W$ |

| Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted | | | | | | |
|--|---------------|--|-------|------|-----------|------------|
| Parameter | Symbol | Test Conditions | Value | | | Unit |
| | | | Min. | Typ. | Max. | |
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = -250\mu A$ | -30 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -30V, V_{GS} = 0V$ | -- | -- | -1 | μA |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20V$ | -- | -- | ± 100 | nA |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\mu A$ | -1 | -1.4 | -2.5 | V |
| Drain-Source On-Resistance | $R_{DS(on)}$ | $V_{GS} = -10V, I_D = -5A$ | -- | 15 | 18 | m Ω |
| | | $V_{GS} = -4.5V, I_D = -5A$ | -- | 20 | 25 | |
| Forward Transconductance | g_{FS} | $V_{DS} = -5V, I_D = -5A$ | -- | 12 | -- | S |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0V,$ $V_{DS} = -4.5V,$ $f = 1.0\text{MHz}$ | -- | 1786 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 237 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 208 | -- | |
| Total Gate Charge | Q_g | $V_{DD} = -15V,$ $I_D = -4.5A,$ $V_{GS} = -10V$ | -- | 18 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 3.4 | -- | |
| Gate-Drain Charge | Q_{gd} | | -- | 3 | -- | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD} = -15V,$ $I_D = -4.5A,$ $R_G = 1\Omega$ | -- | 6 | -- | ns |
| Turn-on Rise Time | t_r | | -- | 3 | -- | |
| Turn-off Delay Time | $t_{d(off)}$ | | -- | 21 | -- | |
| Turn-off Fall Time | t_f | | -- | 3 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I_S | $T_C = 25^\circ\text{C}$ | -- | -- | -9 | A |
| Body Diode Voltage | V_{SD} | $T_J = 25^\circ\text{C}, I_{SD} = -5A, V_{GS} = 0V$ | -- | -- | -1.2 | V |
| Reverse Recovery Charge | Q_{rr} | $I_F = -4.5A, V_{GS} = 0V$ $di/dt = -500A/\mu s$ | -- | 13 | -- | nC |
| Reverse Recovery Time | T_{rr} | | -- | 8.5 | -- | ns |

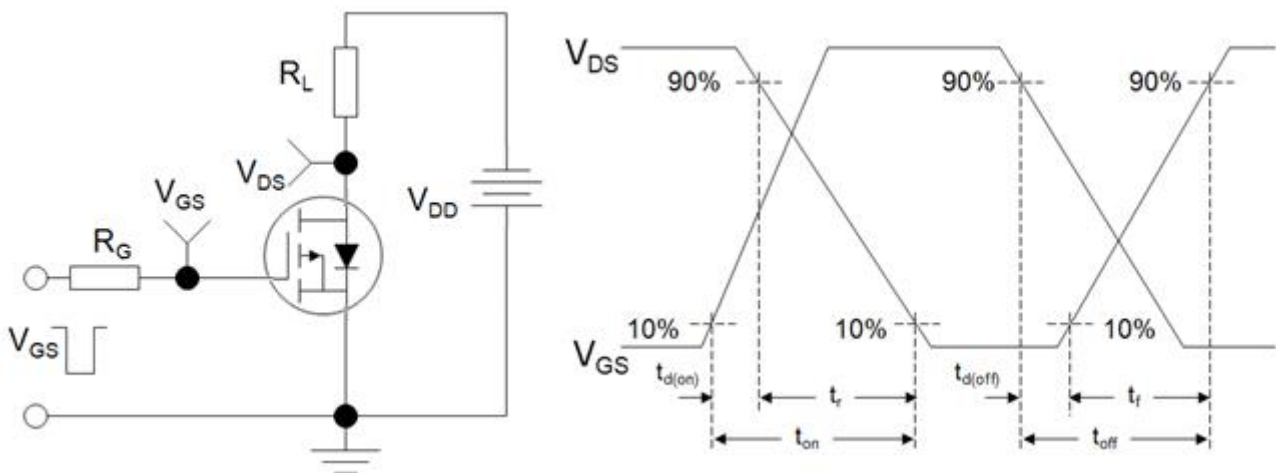
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G

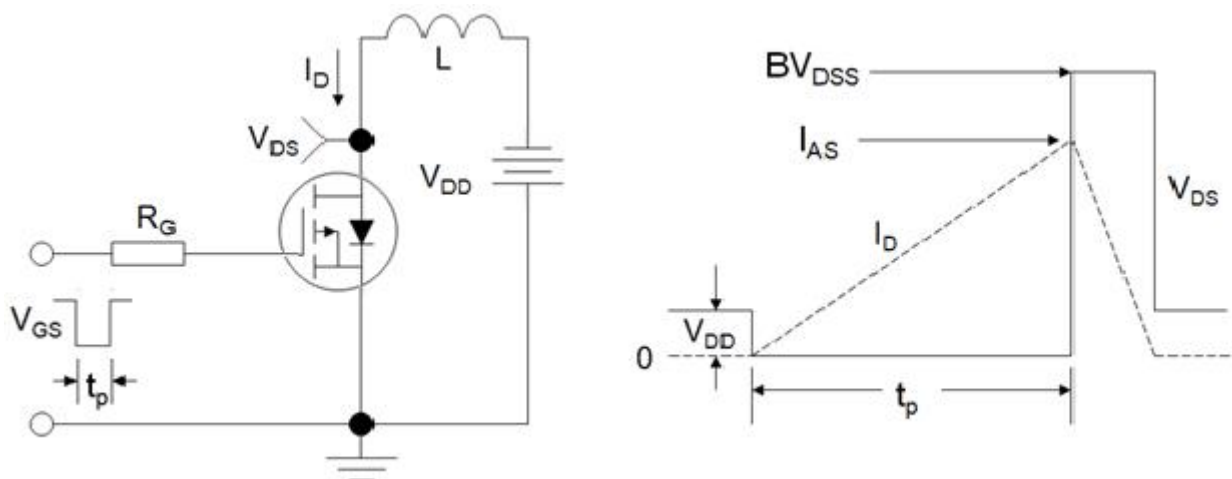
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

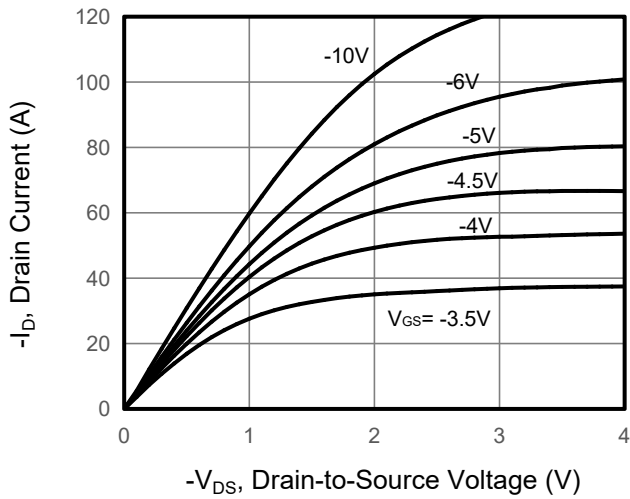


Figure 2. Transfer Characteristics

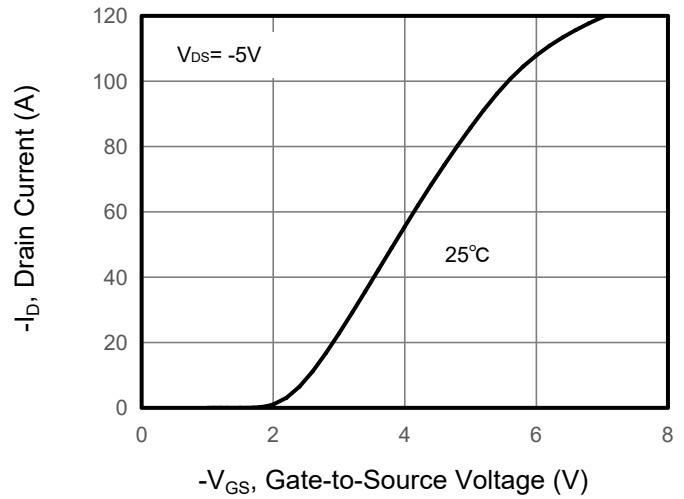


Figure 3. Drain Source On Resistance

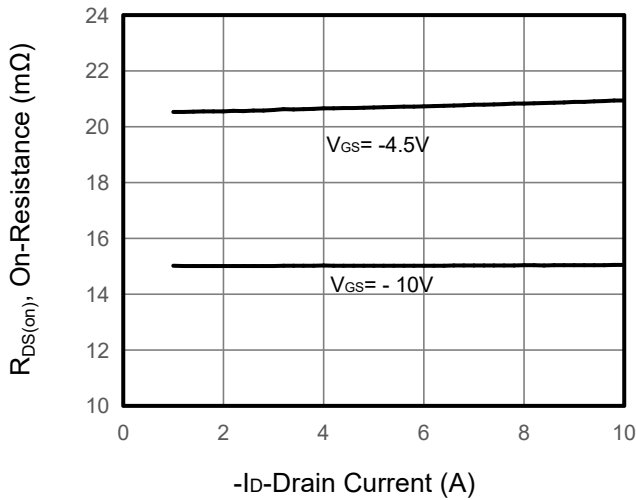


Figure 4. Gate Charge

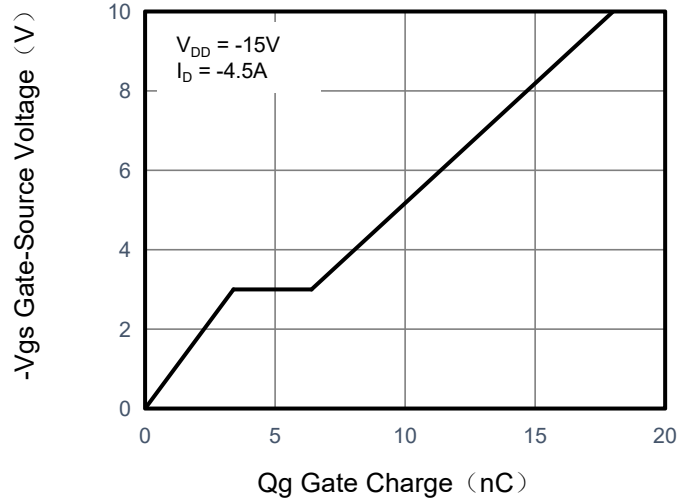


Figure 5. Capacitance

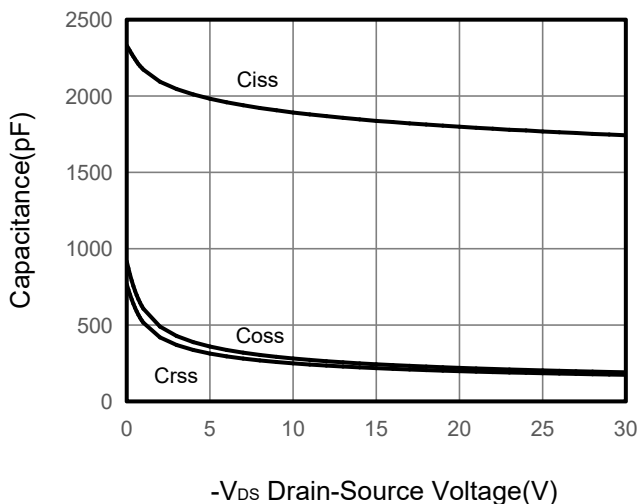
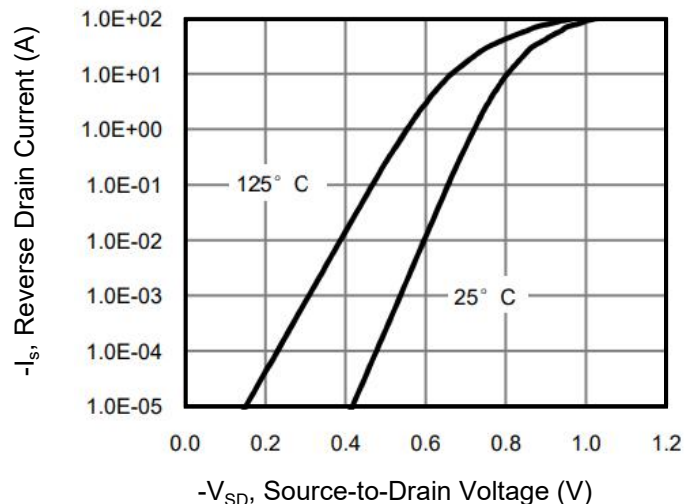


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

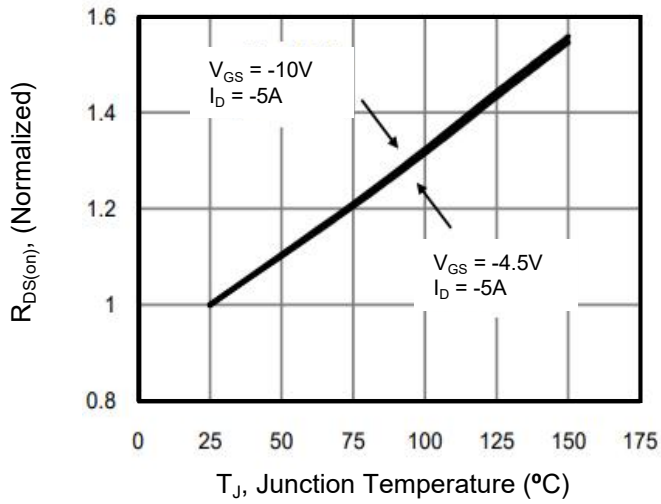


Figure 10. Safe Operation Area

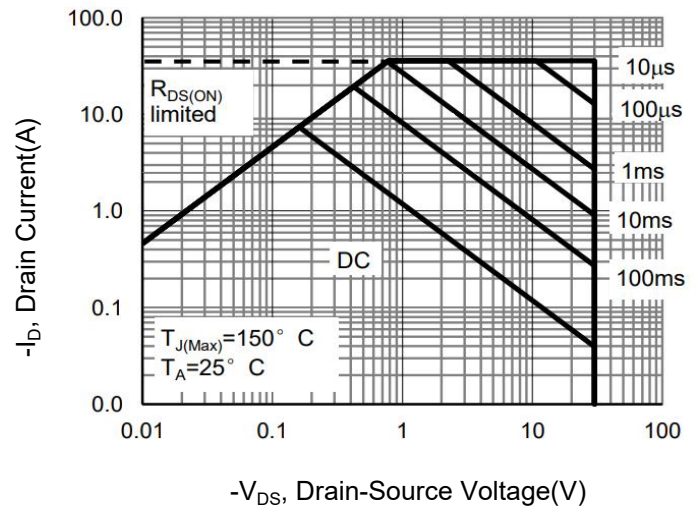
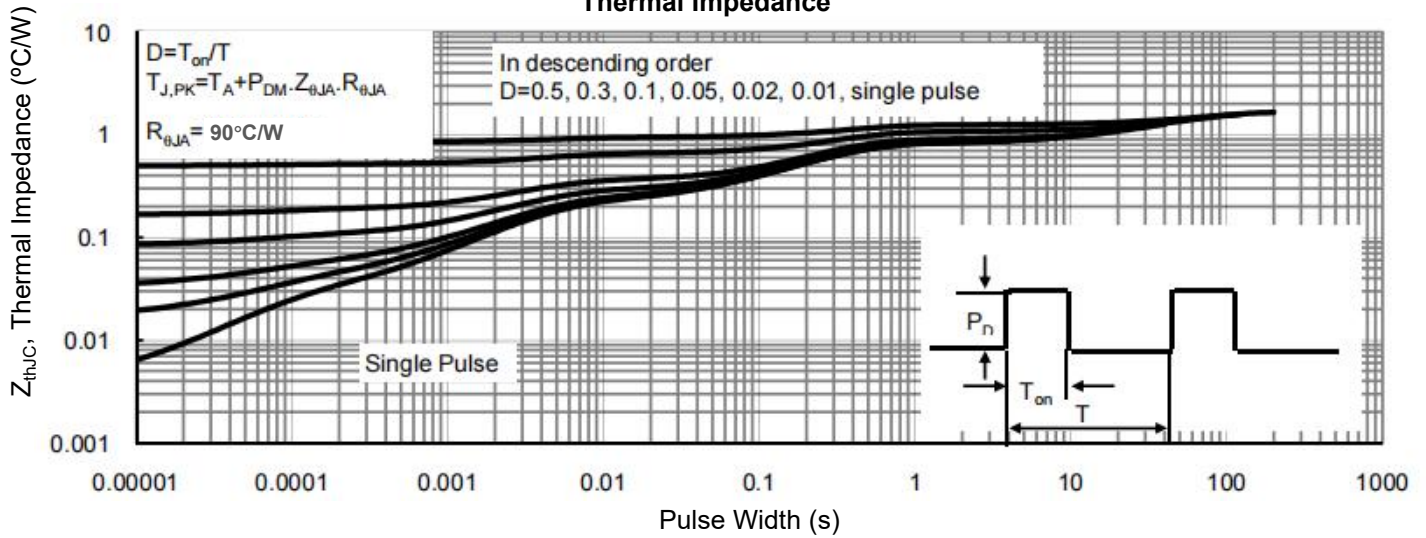
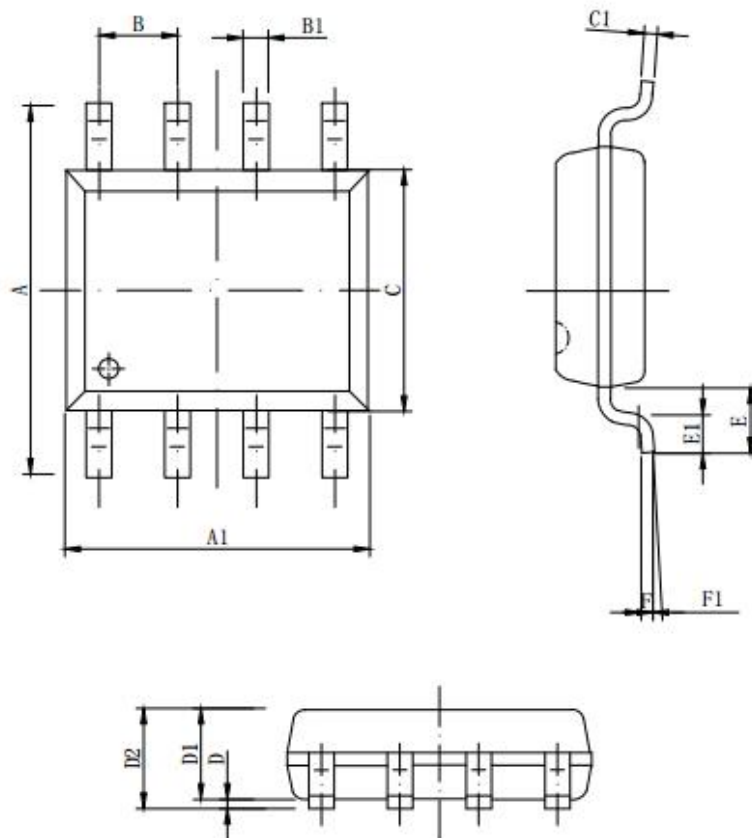


Figure 9. Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



| Symbol | Dimensions in Millimeters | | |
|--------|---------------------------|--------------------|--------------------|
| | MIN. | NOM. | MAX. |
| A | 5.800 | 6.000 | 6.200 |
| A1 | 4.800 | 4.900 | 5.000 |
| B | 1.270BSC | | |
| B1 | 0.35 ^{8x} | 0.40 ^{8x} | 0.45 ^{8x} |
| C | 3.780 | 3.880 | 3.980 |
| C1 | -- | 0.203 | 0.253 |
| D | 0.050 | 0.150 | 0.250 |
| D1 | 1.350 | 1.450 | 1.550 |
| D2 | 1.500 | 1.600 | 1.700 |
| D2 | 1.500 | 1.600 | 1.700 |
| E | 1.060REF | | |
| E1 | 0.400 | 0.700 | 0.100 |
| F | 0.250BSC | | |
| F1 | 2° | 4° | 6° |